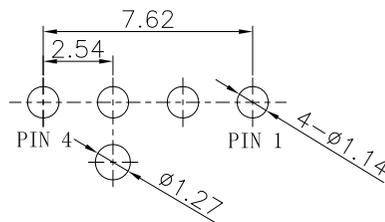
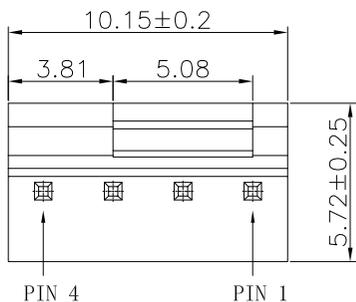
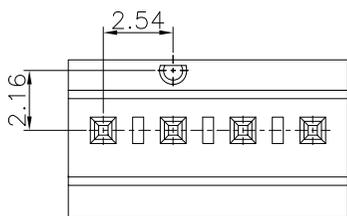
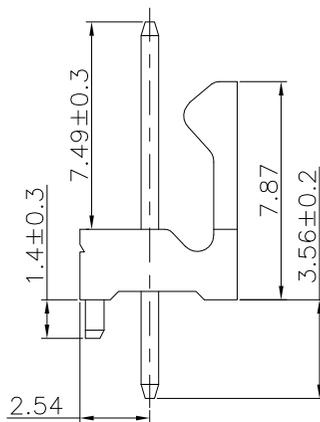
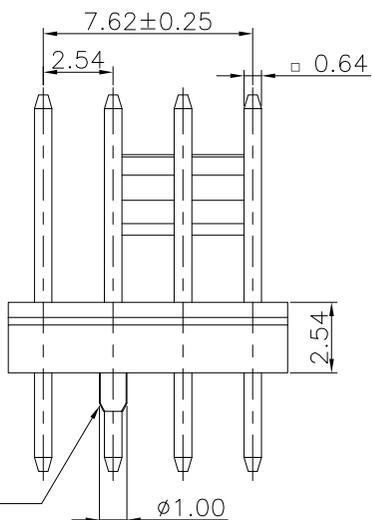


The product using material and processing must conform to the "WI-PZ-001"HSF technical standard control requirements

RoHS+HF



SUGGESTED PCB LAYOUT
(COMPONENT SIDE)



NOTE:

- 1.MATERIAL SPECIFICATION:
 - 1-1.HOUSING: PA66,UL94V-0
 - 1-2.CONTACTS: BRASS
- 2.PLATING SPECIFICATION:
 - 2-1.CONTACTS: TIN/GOLD FLASH PLATED OVER ALL.
- 3.MECHANICAL PERFORMANCE:
 - 3-1.RETENTIVITY FORCE: 1.2KGF/pin min
 - 3-2.DURABILITY: 50 CYCLES.
- 4.ELECTRICAL PERFORMANCE:
 - 4-1.CURRENT RATING: 3A
 - RATED VOLTAGE : 250V AC/DC
 - 4-2.CONTACT RESISTANCE: 20 mΩ MAX
 - 4-3.INSULATION RESISTANCE: 1000MΩ Min
 - 4-4.DIELECTRIC WITHSTANDING : 750V
- 5.ENVIRONMENTAL PERFORMANCE:
 - 5-1.OPERATING TEMPERATURE: -40°C~+105°C.
- 6.PACKAGE SPEC:PE BAG
- 7.P/N:

SERIES NO: A2544 W 0 1-1 XX 1 X X X
 CONNECTOR: W-WAFER
 ANGLE: 0-180°
 TYPE: 1-TYPE 1
 ROW NO: 1-SINGLE ROW
 PIN Q' PY: 02~04
 WATER CODE: 0-N/A
 COLOR: A-BLACK, S-NATURE
 PLATING: A-ALL AU G/F, C-BRIGHT TIN, D-MATTE Tin
 TERMIPOINT: 1-DIP

REV.	REVISION RECORD	DATE	GENERAL TOLERANCES		SCALE: 1:1	NAME	DATE	PART.NO:	DWG.NO:	 WanLian Technology Co., Ltd
AO	NEW RELEASE	21.10.12	LINEAR	ANGLES	APPROVED	Wang_jr	21.10.12	A2544W01-1XX1XXX	ENDE05	
			0.0±0.35	X'REF±6°	DESIGNER	Han_Gao	21.10.12	TITLE:		
			UNIT: mm	0.00±0.25	X'±3°	DRAWN	Zijun_Huang	21.10.12	Pitch 2.54mm 单排180° 立插半靠背带柱 Wafer	
			SIZE: A4	0.000±0.10	X'X' ±2°					